



藤森 亨 **TORU FUJIMORI**

2020. 11. 6

**FUJIFILM Corporation**

**Electronic Materials Research Laboratories  
R&D Management Headquarters**



# *How to reduce the stochastic issue in EUV lithography ?*

藤森 亨

**TORU FUJIMORI**

2020. 11. 6

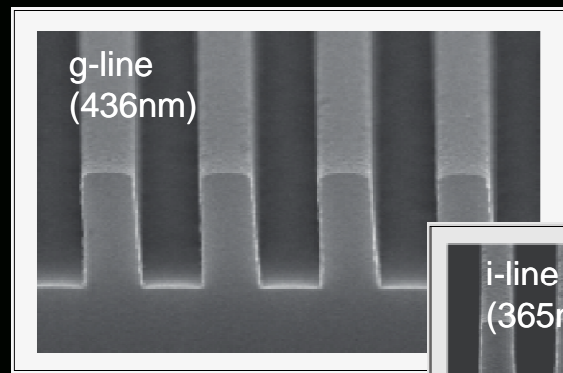
**FUJIFILM Corporation**

**Electronic Materials Research Laboratories  
R&D Management Headquarters**

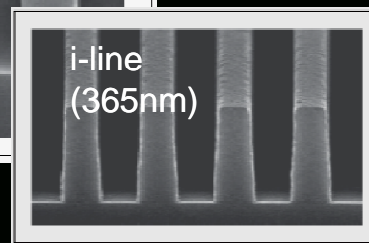


# The Pattern shrinkage history

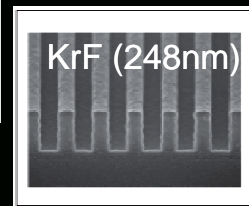
**Pattern shrinkage has been driven  
by shorter exposure wave length.**



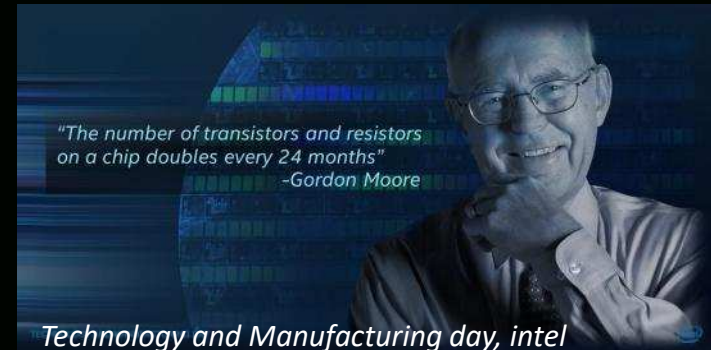
CD = 500nm



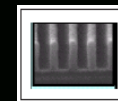
350 nm



150 nm



ArF  
(193nm)



ArFi  
(134nm  
eq.)



EUV  
(13.5nm)

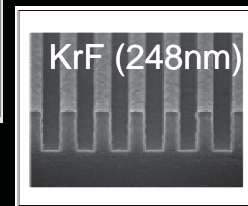
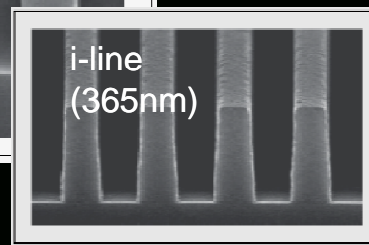
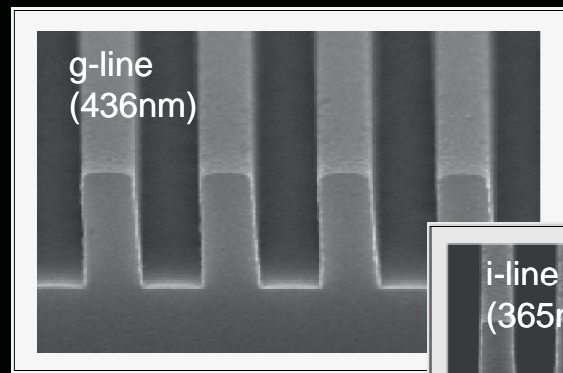


**Pattern Shrinkage : " Never Stop "**  
**Resist materials development : " Never Stop "**

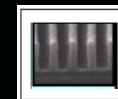


# The Pattern shrinkage history

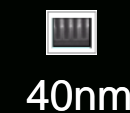
*Pattern shrinkage has been driven  
by shorter exposure wave length.*



ArF  
(193nm)



ArFi  
(134nm  
eq.)



EUV  
(13.5nm)



**EUV lithography**

**Too difficult to apply for manufacturing  
for a long time**

**Pattern Shrinkage : “ Never Stop ”**

**Resist materials development : “ Never Stop ”**

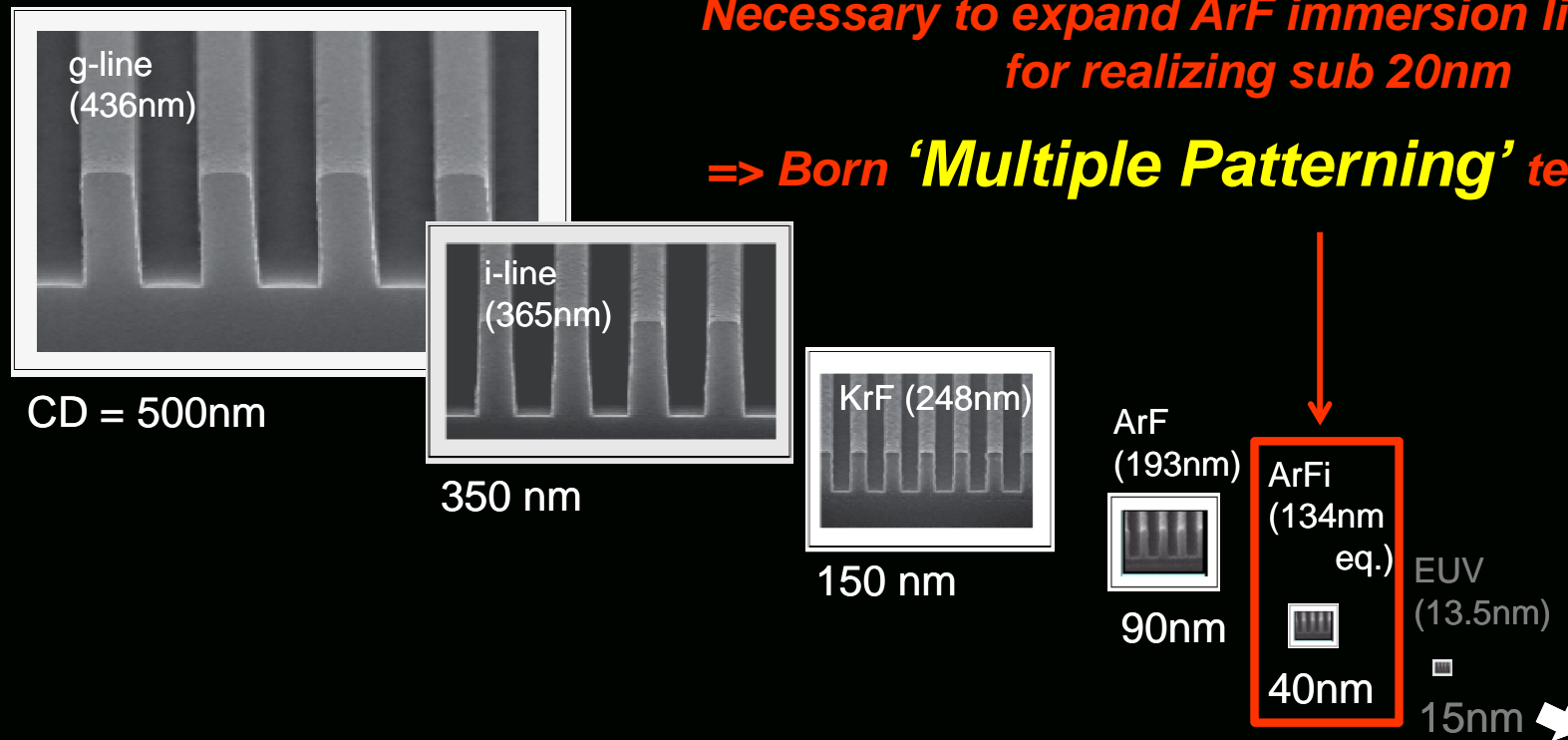


# The Pattern shrinkage history

**Pattern shrinkage has been driven  
by shorter exposure wave length.**

**Necessary to expand ArF immersion lithography  
for realizing sub 20nm**

**=> Born 'Multiple Patterning' technology**

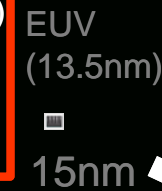
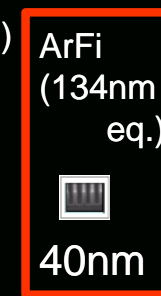
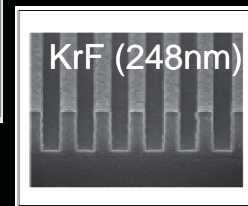
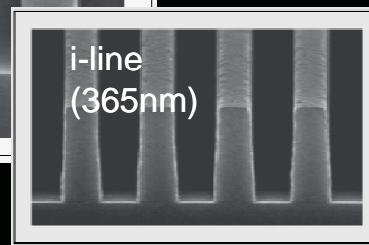
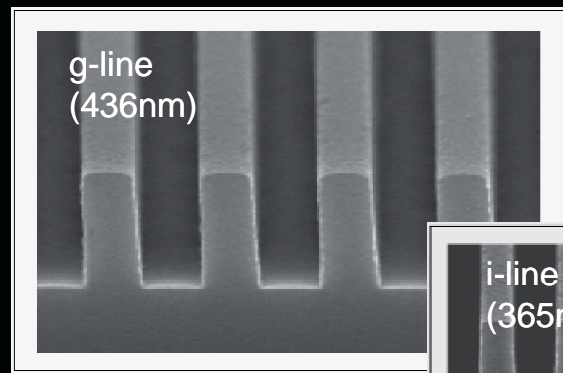


**Pattern Shrinkage : " Never Stop "**  
**Resist materials development : " Never Stop "**



# The Pattern shrinkage history

**Pattern shrinkage has been driven  
by shorter exposure wave length.**



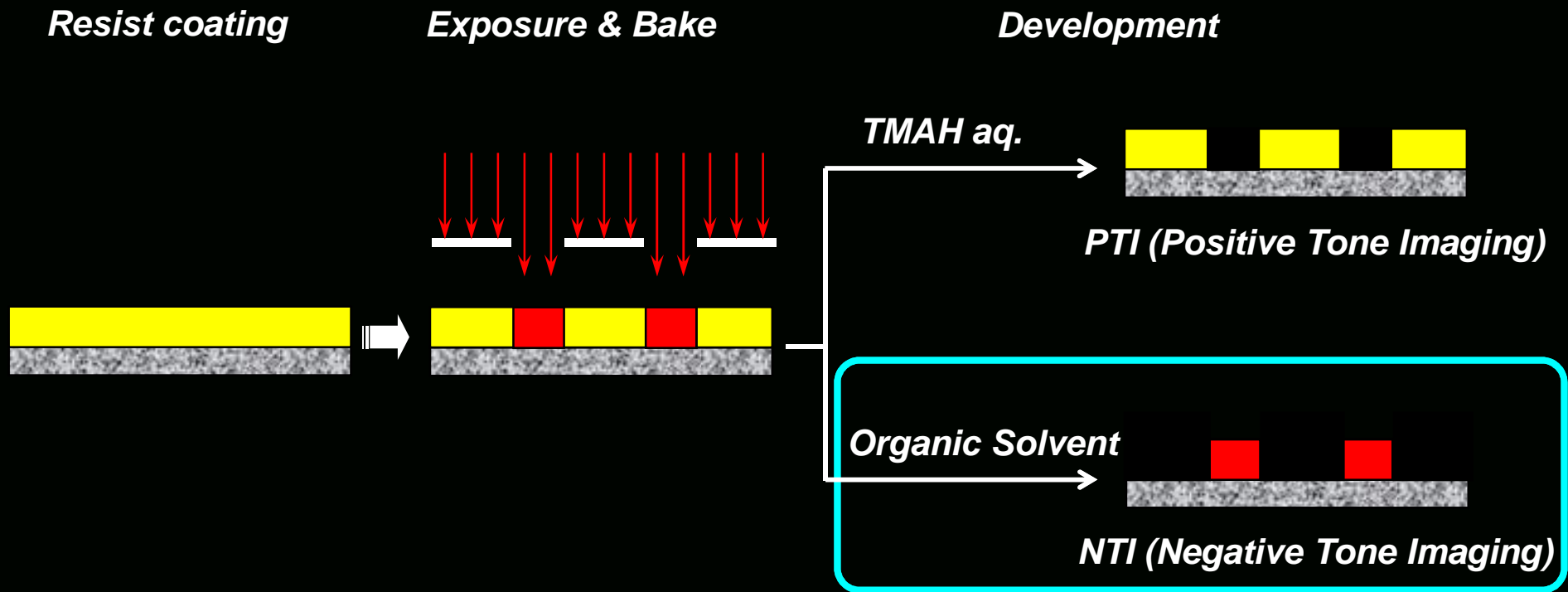
**New technology 'Negative tone Imaging' was  
developed for applying to multiple patterning  
by FUJIFILM**

**Resist materials development : "Never Stop"**



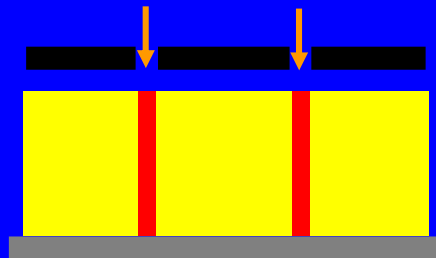
# *The process flow of the lithography*

## *PTI (Positive Tone Imaging) & NTI (Negative Tone Imaging)*

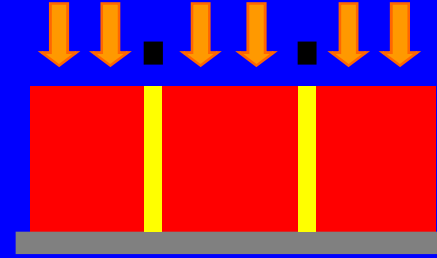
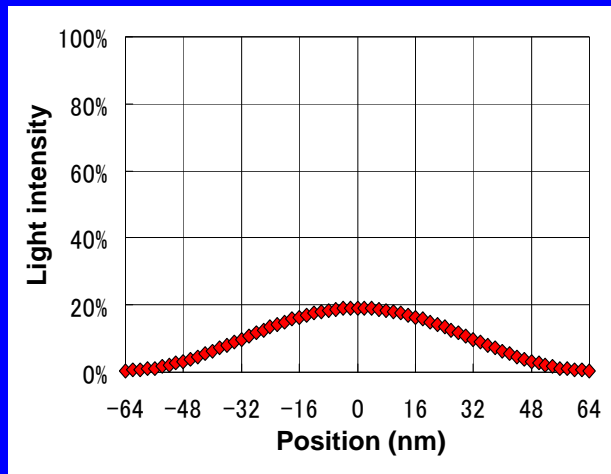


**Resist materials development : “ Never Stop ”**

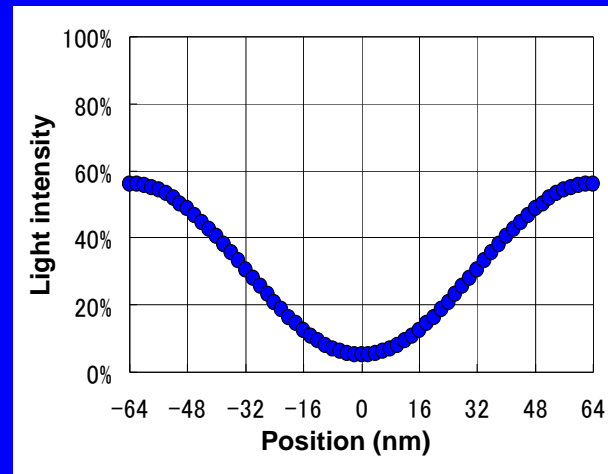
# Theory of Optical Contrast Utilization (PTI vs NTI) FUJIFILM Value from Innovation



Prepare Trench pattern  
by PTI



Prepare Trench pattern  
by NTI



Trench  
pattern  
32nm 1:3

*High resolution can be expected by strong contrast with NTI process.*

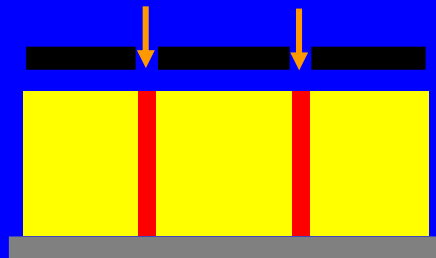
*Resist materials development : " Never Stop "*



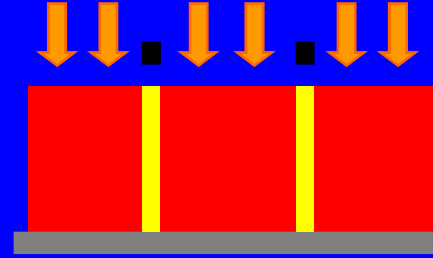
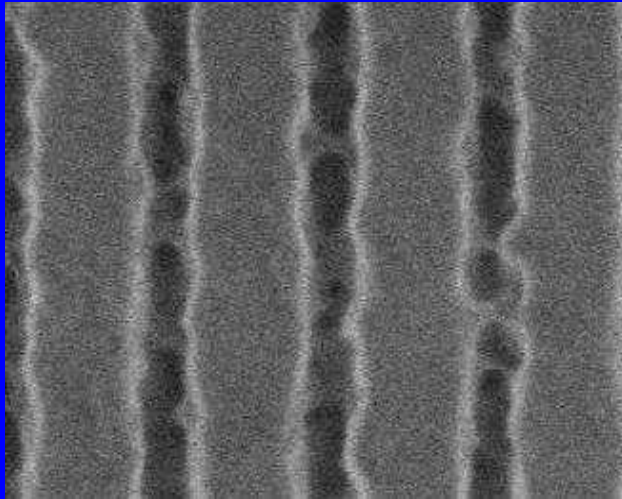


# The resulting patterning comparison (PTI vs NTI)

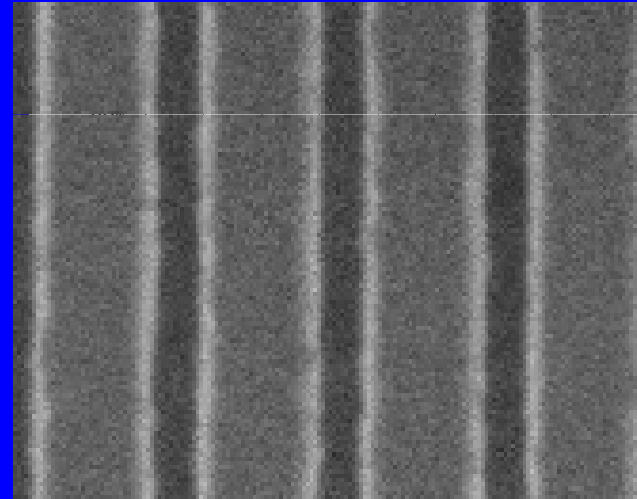
FUJIFILM  
Value from Innovation



Prepare Trench pattern  
by PTI



Prepare Trench pattern  
by NTI



Trench  
pattern  
32nm 1:3

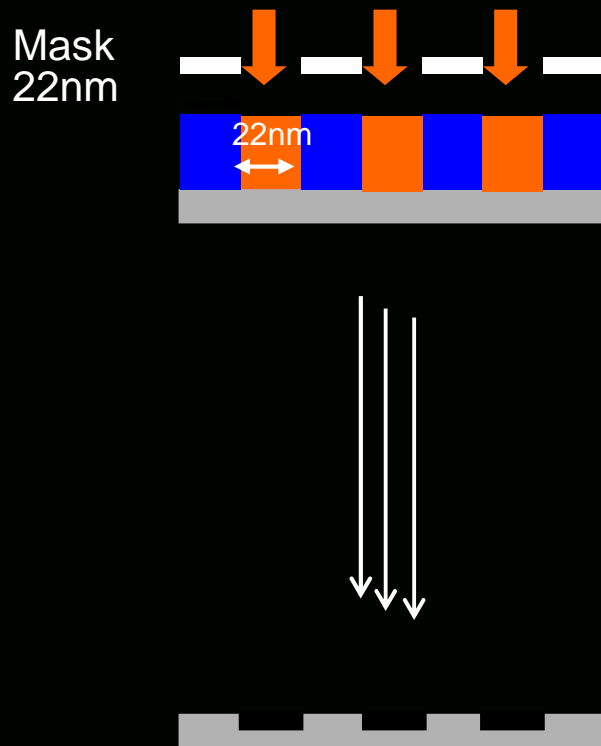
*NTI process observed brilliant resolution,  
useful for multiple patterning !!*

*Resist materials development : "Never Stop"*

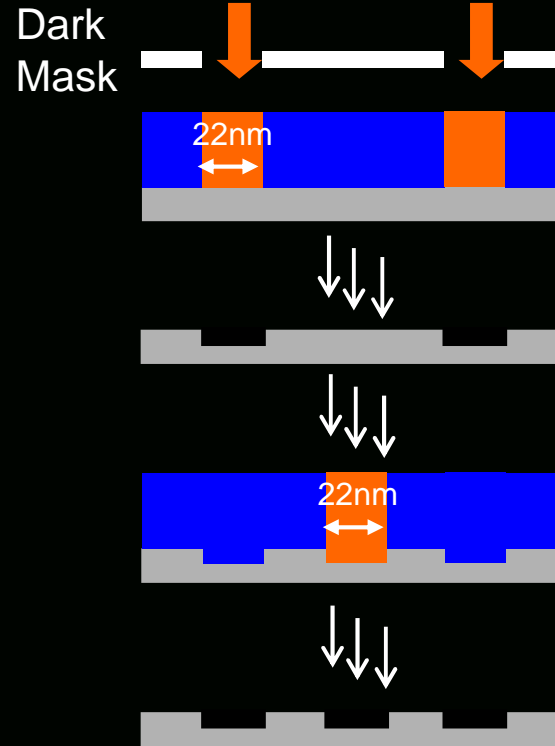
NEVER  
STOP

# What is NTI useful for ? *Ex) Prepare P44nm LS (1:1)*

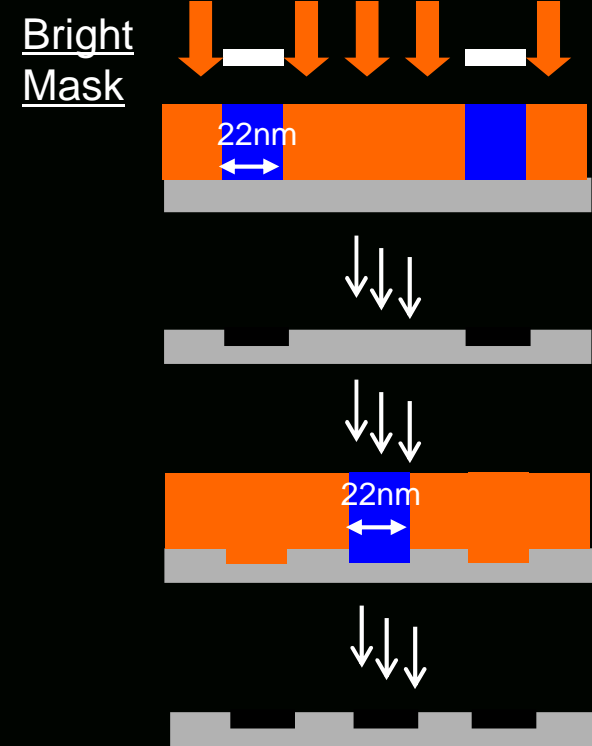
## Single Patterning Pitch=44nm



## Double Patterning Pitch=88nm with PTI



## Double Patterning Pitch=88nm *with NTI*

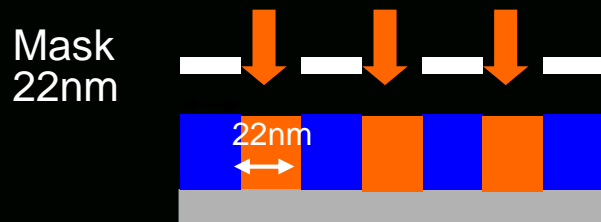


*Resist materials development : " Never Stop "*

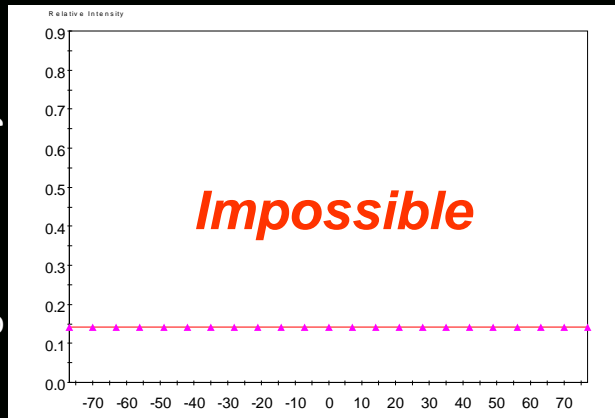


# What is NTI useful for ? *Ex) Prepare P44nm LS (1:1)*

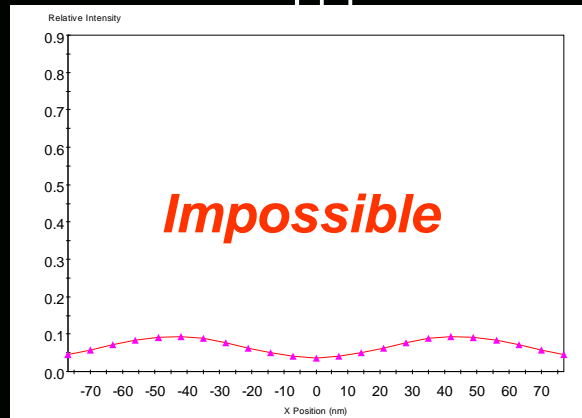
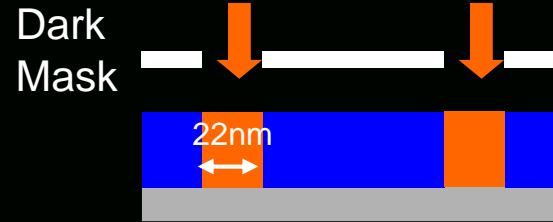
## Single Patterning Pitch=44nm



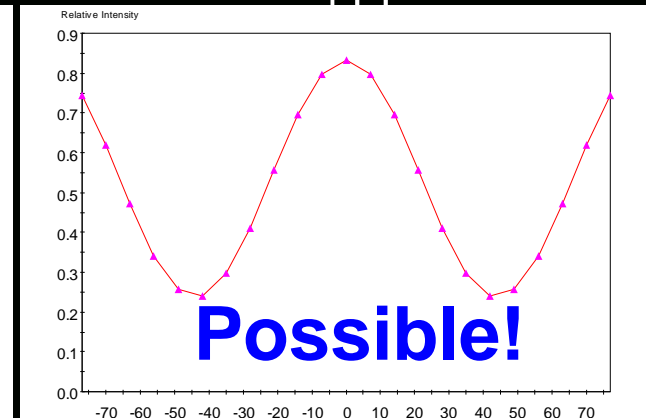
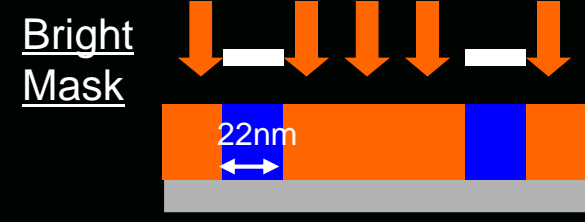
Light Intensity



## Double Patterning Pitch=88nm with PTI



## Double Patterning Pitch=88nm *with NTI*



Resist materials development : "Never Stop"

# What is NTI useful for ? EX. Double patterning.

Only 'Double patterning with NTI' can be observed brilliant patterns !

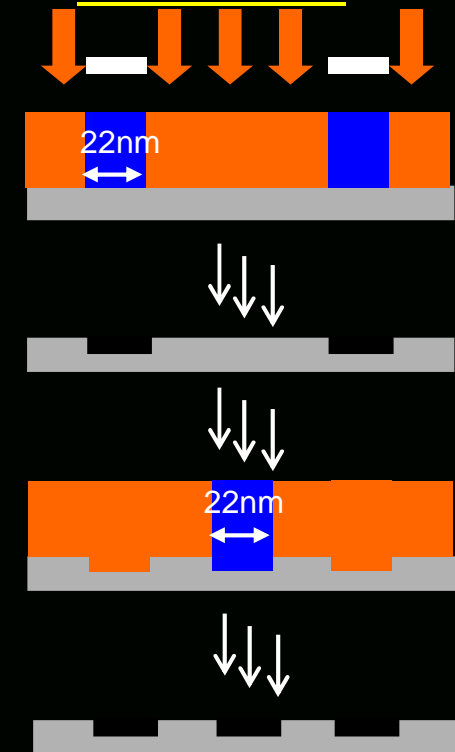
Of course, can be applied to **multiple patterning** !

Also, 'Developer' is very important.  
Has to be used 'Ultra pure solvent'.

## Double Patterning

Pitch=88nm

**with NTI**



Resist materials development : " Never Stop "



# History of EUV lithography

*In 2018*

Qualcomm  
released SD 855 !



*Impress Watch*

**7nm** design rule  
( Already installed to smart phone in 2019 )

By using **ArFi** multi-patterning **w/o EUV** litho  
Lots of **NTI process** were used.

However,  
for manufacturing of next generation chips,

it necessary to use **EUV lithography** !

**Resist materials development : “ Never Stop ”**



# History of EUV lithography

**Finally, EUV lithography generation has come.**

In 2019 **7nm+** design rule was applied to HVM

by using **EUV** lithography patterning.

Qualcomm  
New chip release !

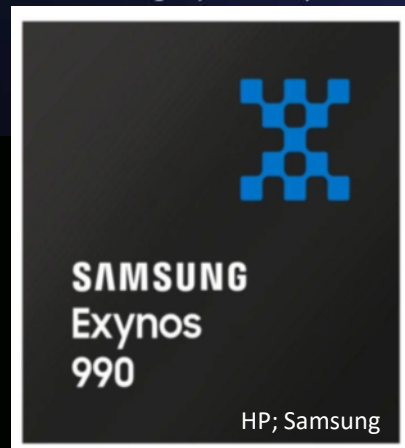


*K-tai. watch. impress*

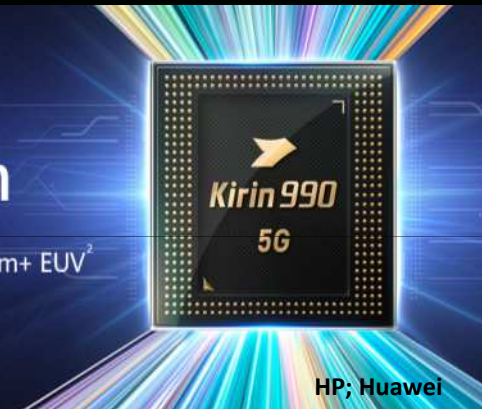
HUAWEI Kirin 990 Series<sup>1</sup>

Rethink Evolution

World's 1st Flagship 5G SoC powered with 7nm+ EUV<sup>2</sup>



HP; Samsung



HP; Huawei



HP; Sharp

**Already installed to  
5G smart phone in 2020**

**Resist materials development : " Never Stop "**



# History of EUV lithography

The first paper of EUV lithography - by Prof. Kinoshita -



Anthony Yen, *EUV lithography: From the very Beginning to the eve of manufacturing* (SPIE 2016)

National Project in Japan

↓  
1996

↓ Selete

↓  
2011

↓ EIDEC

↓  
2019

**Over 23 years !**

**Waiting for EUV lithography  
for a lo-----ng time.**

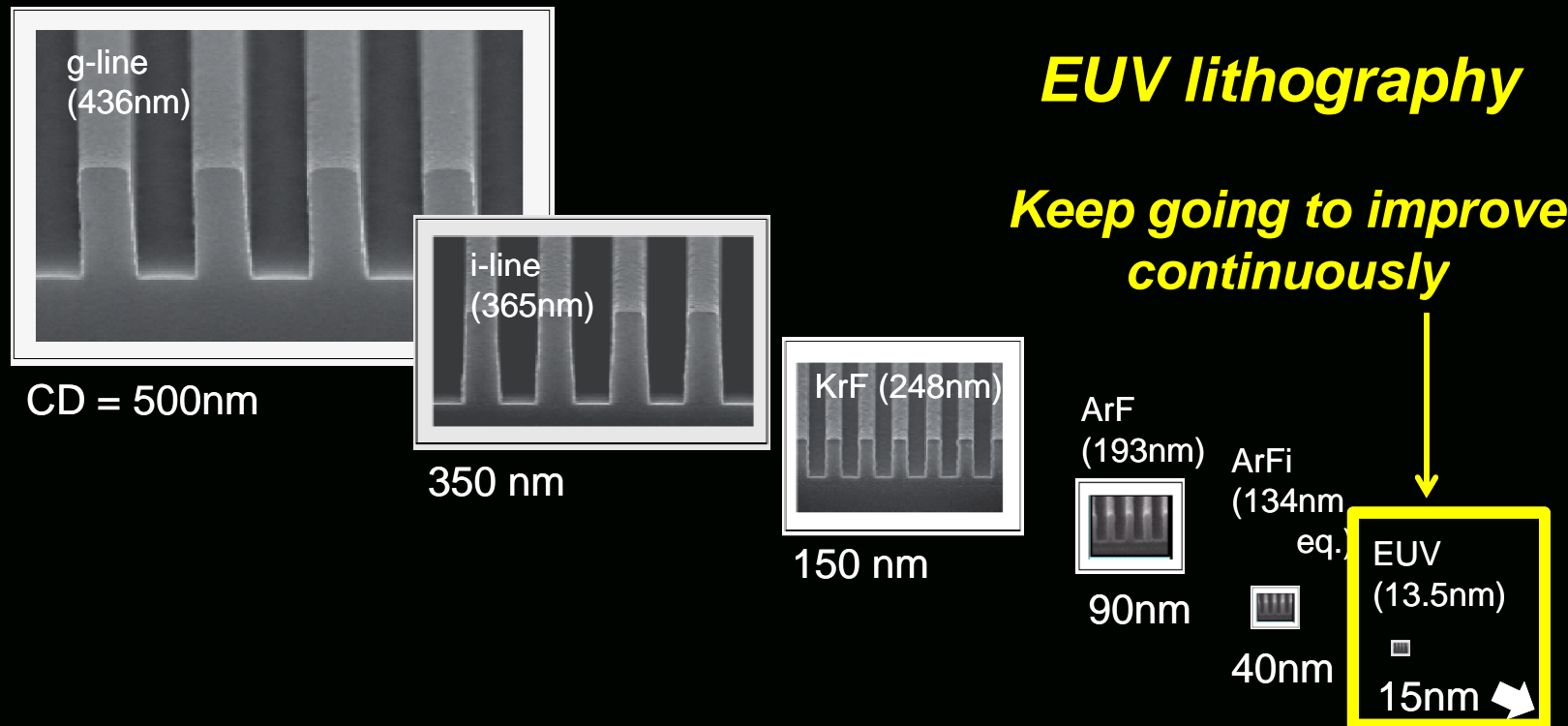
**Finally, *EUV generation has come*  
in 2019, 令和元年(*Reiwa 1*) in Japan.**

**Resist materials development : “ Never Stop ”**



# The Pattern shrinkage history

*Pattern shrinkage has been driven  
by shorter exposure wave length.*



**EUV lithography**

**Keep going to improve  
continuously**

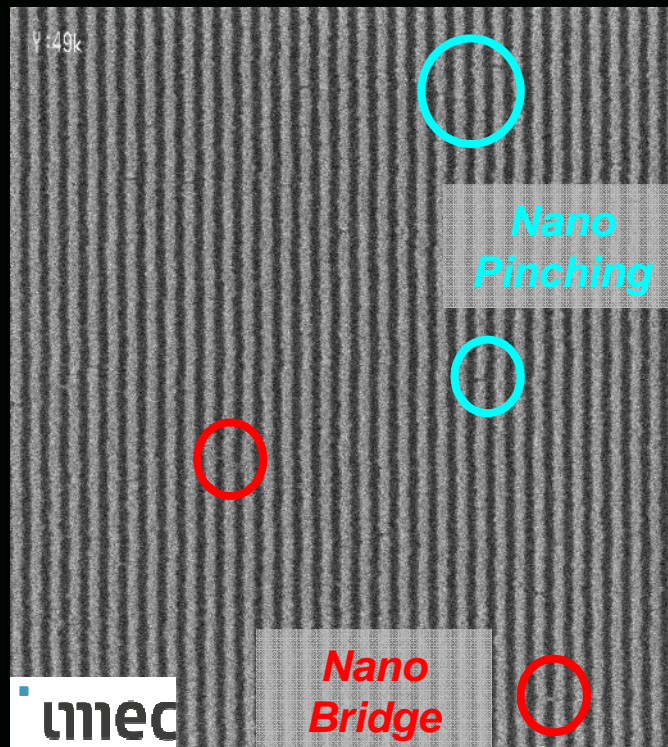
**Pattern Shrinkage : “ Never Stop ”**

**Resist materials development : “ Never Stop ”**





# Challenging of EUV resist



**HP13nm**

$E_{opt} = 42 \text{ mJ/cm}^2$

LWR = 5.3 nm

The **resolution** looks **good enough**.

However,

**“Nano-Bridge”** and **“Nano-Pinching”**  
were observed.

=> **Becomes an obstacle for HVM.**

How to **reduce the stochastic** factor ?

**Resist materials development : “ Never Stop ”**



# What is the stochastic ?

Have you ever heard “**stochastic**” ? Basically, it means...

What is the **stochastic** issues ?

Why now ?? No issues before ?

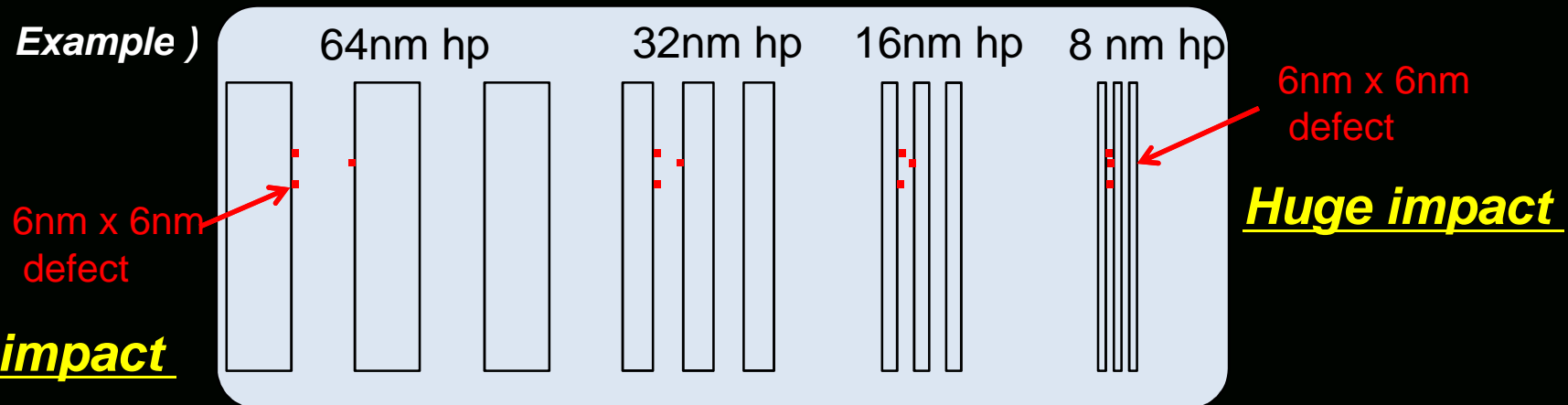
Random

随机

隨機

**Influence of pattern size shrinkage !**

Example )



**Resist materials development : “ Never Stop ”**

NEVER  
STOP

## How to improve the stochastic issues?

### Focus on 2 major Stochastic issues

1. **Photon stochastic** ( photon shot noise )  
( Cause : light source )

Poor photon number.

=> The resist materials can help it.

*Introduce the function* of 'catch more photon'.

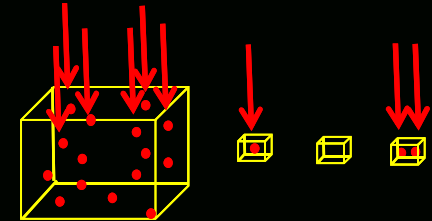
2. **Chemical stochastic**

( Cause : resist )

The materials location randomness in the film.

The reaction randomness in the film.

=> The *functionalized materials* are effective.



*Resist materials development : “ Never Stop ”*



## How to improve the stochastic issues?

### Focus on 2 major Stochastic issues

1. **Photon stochastic** ( photon shot noise )  
( Cause : light source )

Poor photon number.

=> The resist materials can help it.

*Introduce the function* of 'catch more photon'.

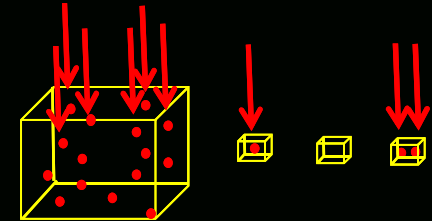
2. **Chemical stochastic**

( Cause : resist )

The materials location randomness in the film.

The reaction randomness in the film.

=> The *functionalized materials* are effective.



*Resist materials development : “ Never Stop ”*



# Improvement of EUV resist performance

## Reaction mechanism of CAR with EUV exposure

1<sup>st</sup> step

Catch the light

2<sup>nd</sup> step

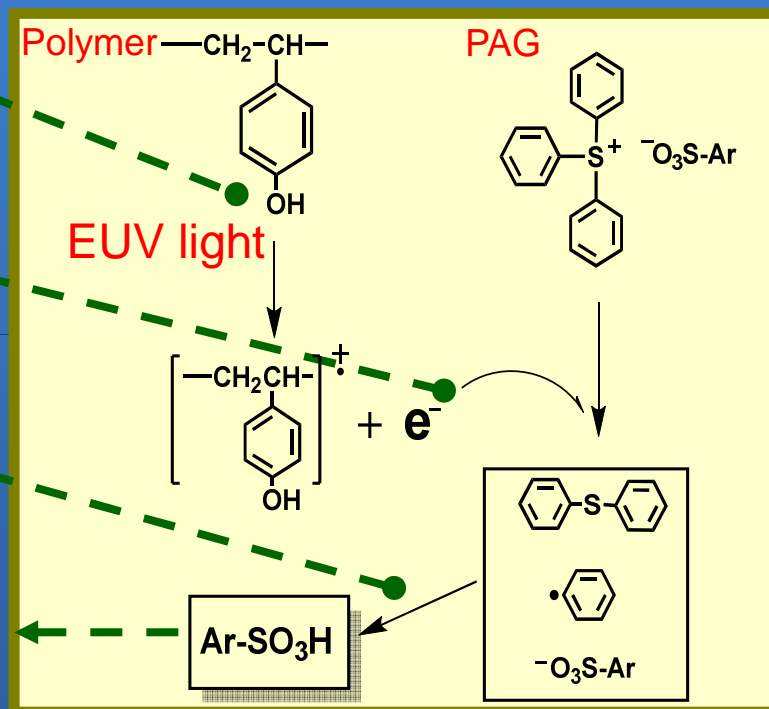
Generate the secondary electron

3<sup>rd</sup> step

Generate the acid

4<sup>th</sup> step

React with acid labile group



1<sup>st</sup> / 2<sup>nd</sup> step

*Different* from previous litho.

1<sup>st</sup> step

*(Catch the light)*  
Very important to realize EUV lithography.

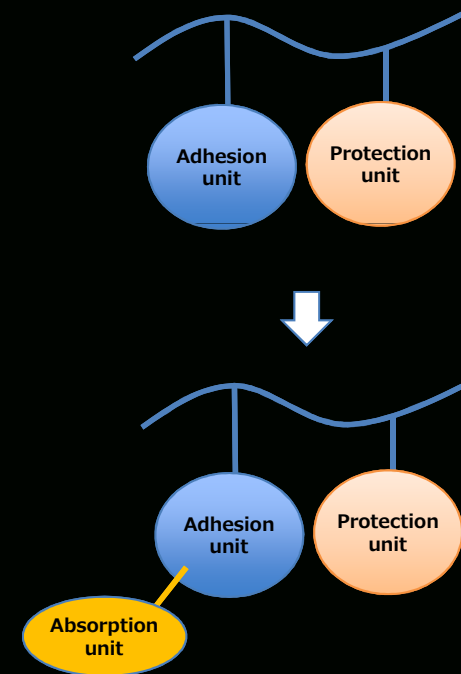
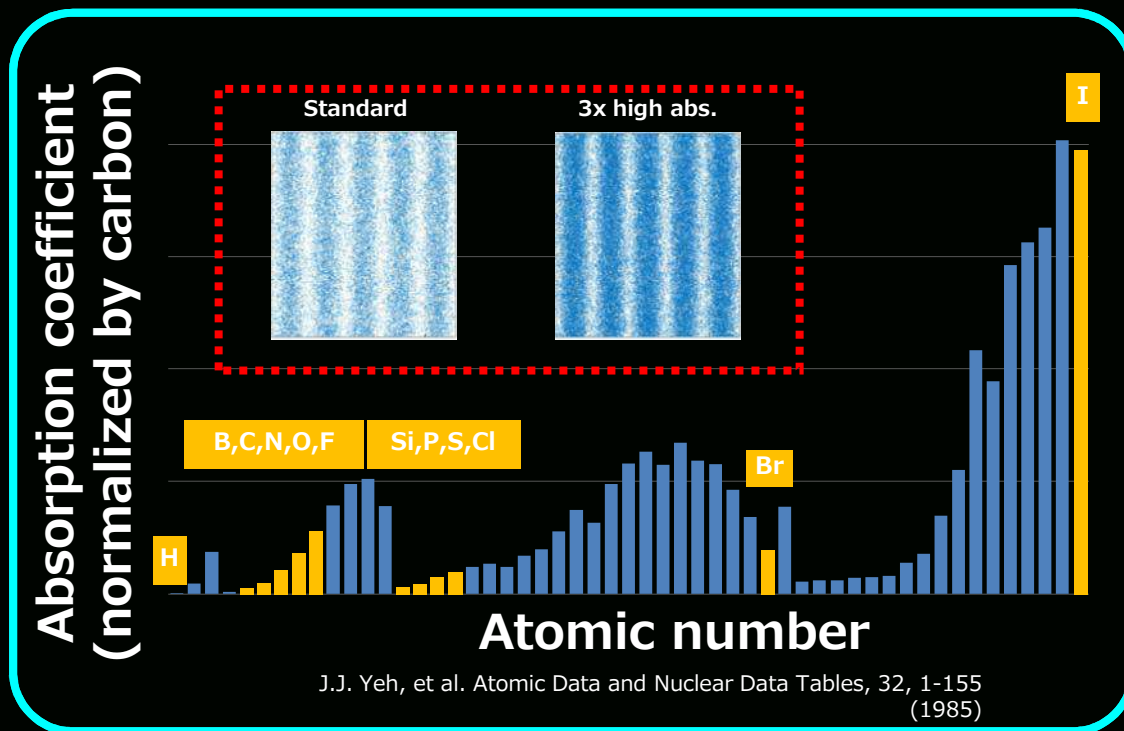
T. Kozawa et al., J. Vac. Sci. Technol. B, 22, 3489 (2004)

**Resist materials development : "Never Stop"**

NEVER  
STOP

# Organic high-EUV absorption CAR

For realizing to catch the light more efficiency,  
Designed 'Organic high EUV absorption materials'.

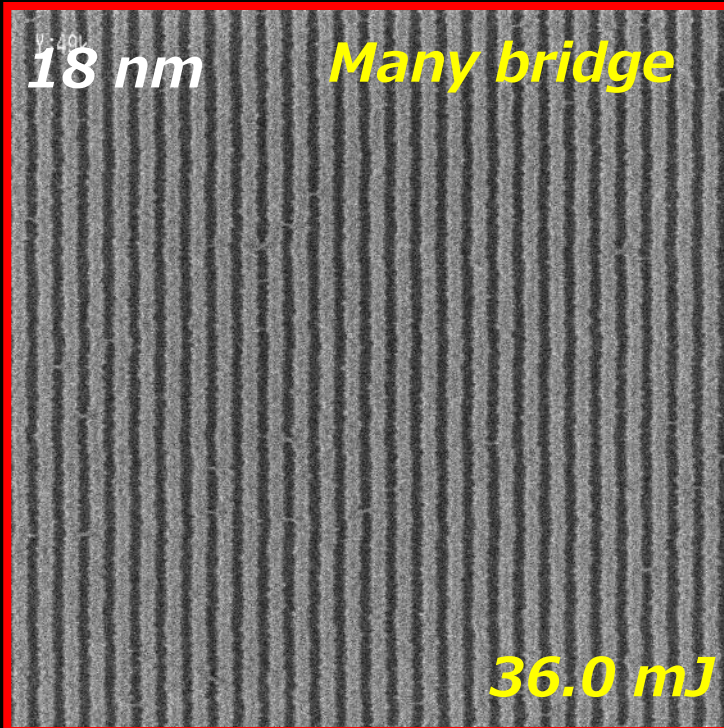


**Resist materials development : " Never Stop "**

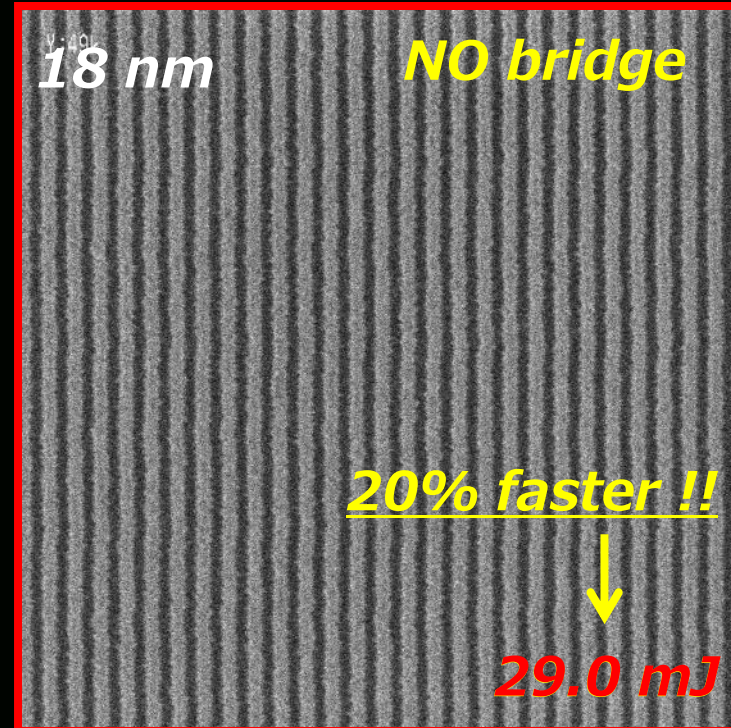


# Organic high-EUV absorption CAR

## Standard type



## High absorption type



Excellent bridging performance with high sensitivity !!

Resist materials development : " Never Stop "



## How to improve the stochastic issues?

### Focus on 2 major Stochastic issues

1. **Photon stochastic** ( photon shot noise )  
( Cause : light source )

Poor photon number.

=> The resist materials can help it.

*Introduce the function* of 'catch more photon'.

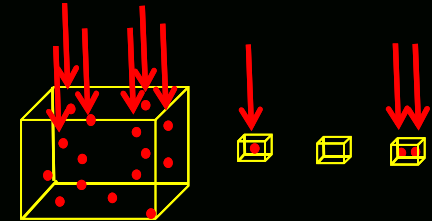
2. **Chemical stochastic**

( Cause : resist )

The materials location randomness in the film.

The reaction randomness in the film.

=> The *functionalized materials* are effective.



*Resist materials development : “ Never Stop ”*





# What is 'Chemical stochastic' ?

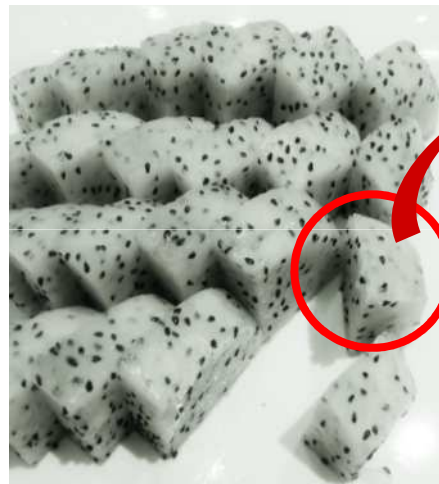
**Chemical stochastic** ( Cause : resist, and/or nature phenomena)

The image of 'Chemical stochastic'

Example) ' Dragon fruits' 火龍果 ,火龙果

Seeds : Chemicals

Fruits : Polymer matrix



Each piece has **own locality** of the seeds.

**The seeds has locality** in one piece.

**Nobody can control the position of the seeds.**

**Resist materials development : " Never Stop "**

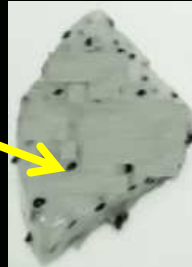
# Fluctuation of quantum efficiency

One of the famous method to reduce 'Chemical stochastic'.

=> **Higher PAG loading** effect.

< Usual PAG loading >

Lots of locality part



< Higher PAG loading >

**Better uniformity**

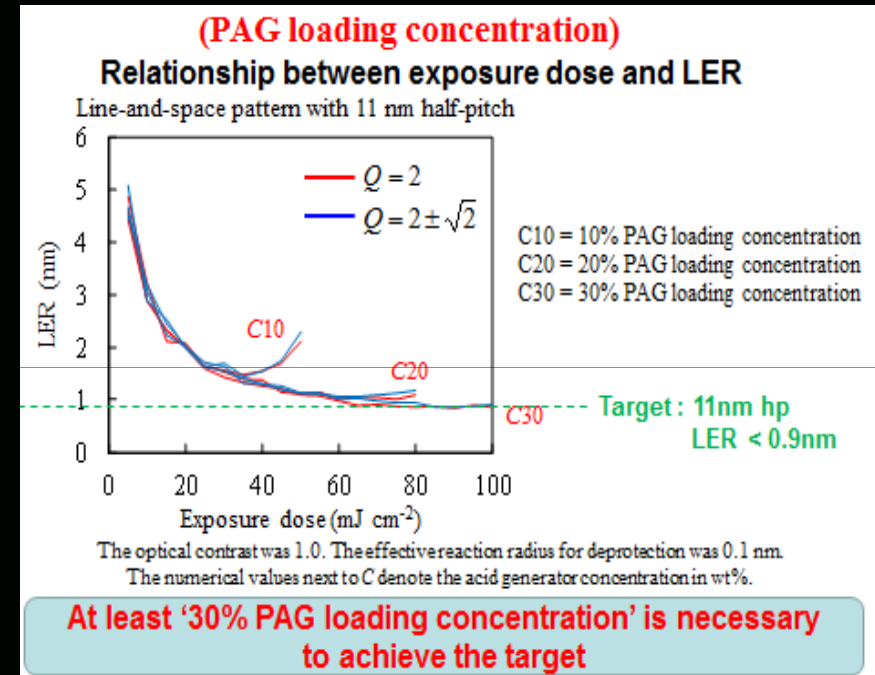
Higher chance to generate acids.

Higher chance to react.



**Improve**  
**'Chemical stochastic' !**

**Expected**  
**Excellent LER !!**

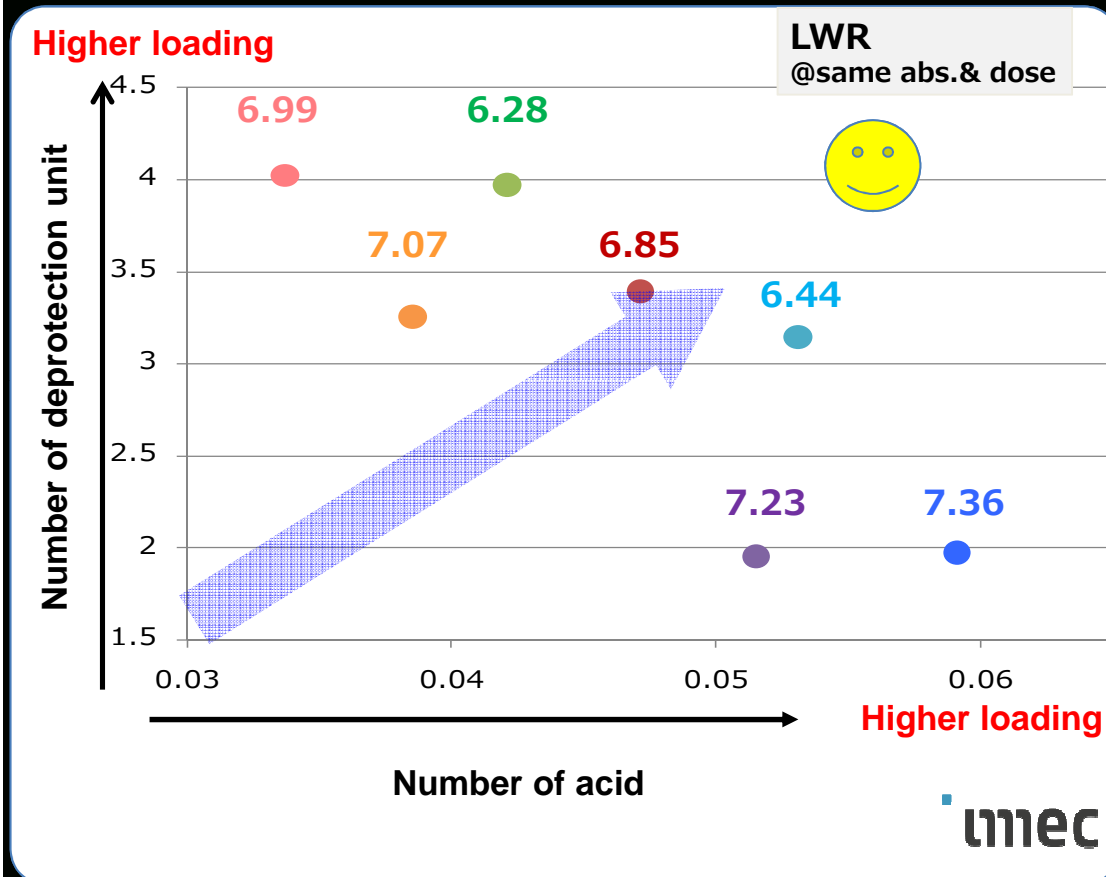


T. Kozawa et al., simulation study with EIDEC.

**Resist materials development : "Never Stop"**

# Fluctuation of quantum efficiency

**Higher loading mitigated stochastic effect.**



PAG higher loading =>

Deprotection unit

higher loading =>

*Higher chance to generate acids.*

*Higher chance to react.*



**Improve**

**'Chemical stochastic' !**

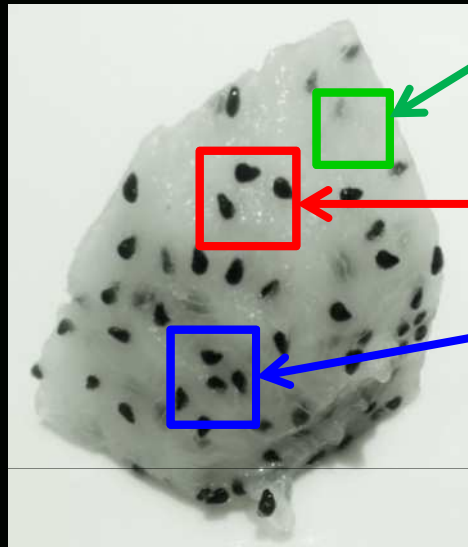


**Indicated excellent LWR !!**

**Resist materials development : " Never Stop "**



# Further improvement of 'Chemical stochastic'

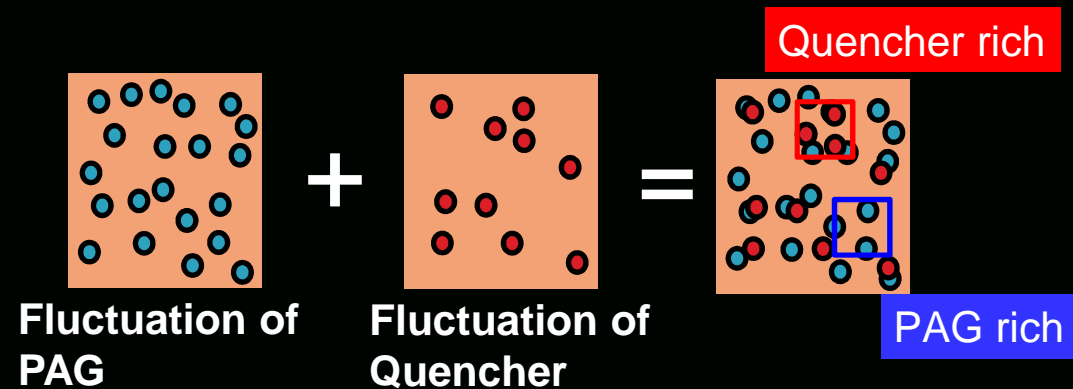


zero

Three

Five

## Current technology



**The seeds has locality  
in one peace.**

**Even, introduced *higher loading technology*,  
still remaining the fluctuation.**

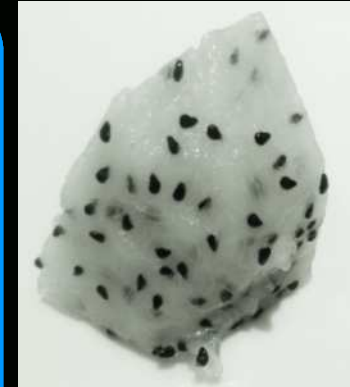
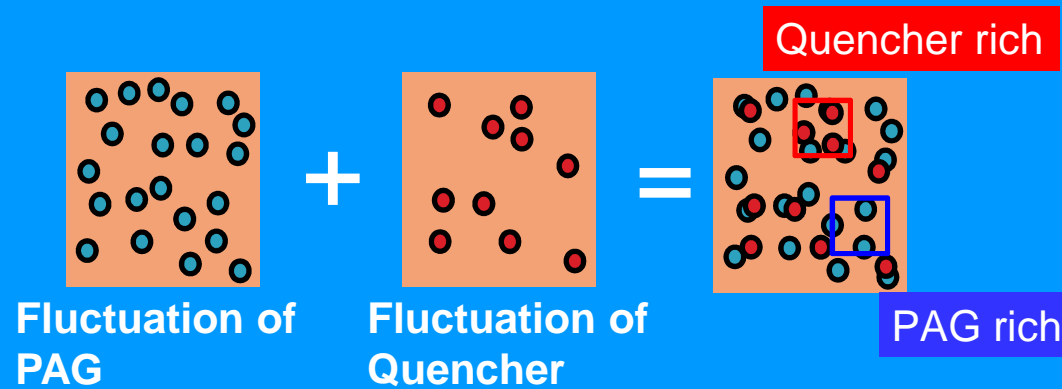
How to control  
of  
the position of seeds ?  
Possible ??

**How to improve ???**

**Resist materials development : " Never Stop "**

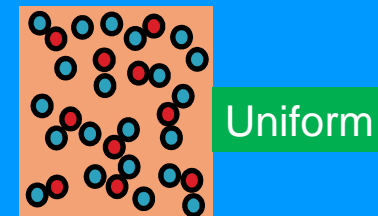
# Further improvement of 'Chemical stochastic'

Current  
technology



New  
technology

Uniform disperse in the film  
by using  
the functionalized materials

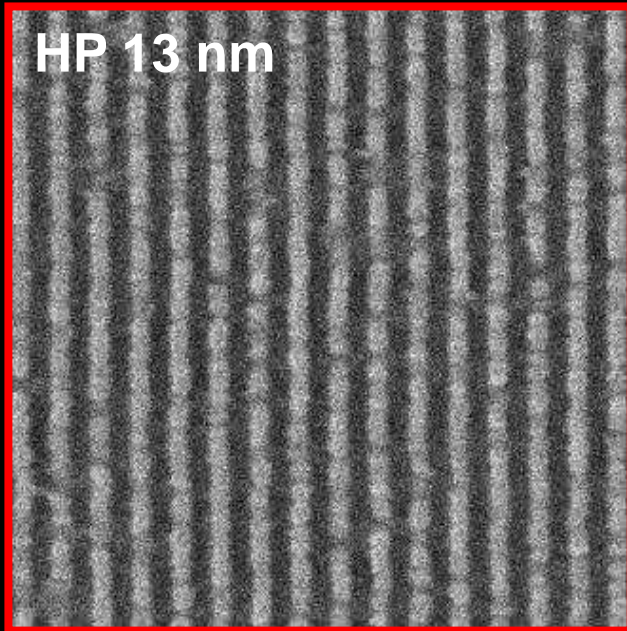


*Improve 'Chemical stochastic'.*

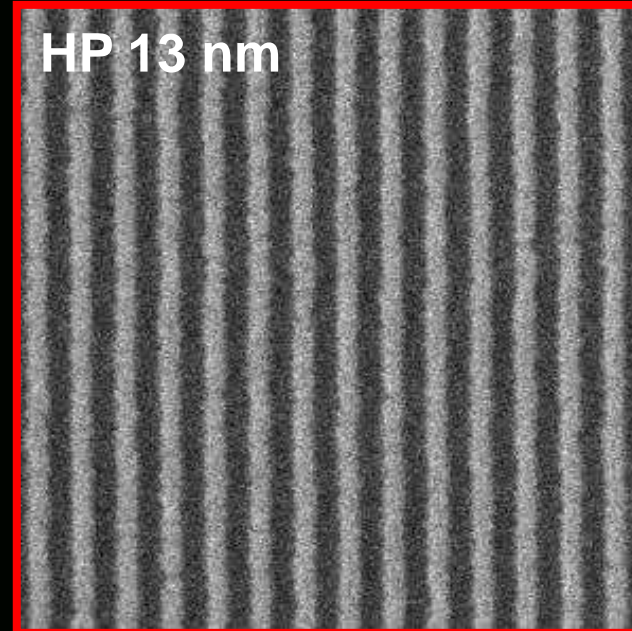
*Resist materials development : " Never Stop "*

## *Further improvement of 'Chemical stochastic'*

**Current technology**



**New technology**



**New technology indicated brilliant performance !!**

**Resist materials development : " Never Stop "**



***Thank you for your kind attention !!***



***If you have any questions, comments,  
or would like to communicate with me,  
please let me know.***

***toru.fujimori@fujifilm.com***

